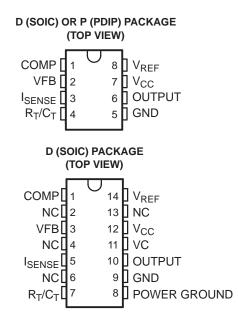
SLVS610B-AUGUST 2006-REVISED JULY 2007

### **FEATURES**

- Low Start-Up Current (<0.5 mA)</li>
- Trimmed Oscillator Discharge Current
- Current Mode Operation to 500 kHz
- Automatic Feed-Forward Compensation
- Latching PWM for Cycle-by-Cycle Current Limiting
- Internally Trimmed Reference With Undervoltage Lockout
- High-Current Totem-Pole Output Undervoltage Lockout With Hysteresis
- Double-Pulse Suppression



NC - No internal connection

### **DESCRIPTION/ORDERING INFORMATION**

The TL284xB and TL384xB series of control integrated circuits provide the features that are necessary to implement off-line or dc-to-dc fixed-frequency current-mode control schemes, with a minimum number of external components. Internally implemented circuits include an undervoltage lockout (UVLO) and a precision reference that is trimmed for accuracy at the error amplifier input. Other internal circuits include logic to ensure latched operation, a pulse-width modulation (PWM) comparator that also provides current-limit control, and a totem-pole output stage designed to source or sink high-peak current. The output stage, suitable for driving N-channel MOSFETs, is low when it is in the off state.

The TL284xB and TL384xB series are pin compatible with the standard TL284x and TL384x with the following improvements. The start-up current is specified to be 0.5 mA (max), while the oscillator discharge current is trimmed to 8.3 mA (typ). In addition, during undervoltage lockout conditions, the output has a maximum saturation voltage of 1.2 V while sinking 10 mA ( $V_{CC} = 5 \text{ V}$ ).

Major differences between members of these series are the UVLO thresholds and maximum duty-cycle ranges. Typical UVLO thresholds of 16 V (on) and 10 V (off) on the TLx842B and TLx844B devices make them ideally suited to off-line applications. The corresponding typical thresholds for the TLx843B and TLx845B devices are 8.4 V (on) and 7.6 V (off). The TLx842B and TLx843B devices can operate to duty cycles approaching 100%. A duty-cycle range of 0% to 50% is obtained by the TLx844B and TLx845B by the addition of an internal toggle flip-flop, which blanks the output off every other clock cycle. The TL284xB-series devices are characterized for operation from  $-40^{\circ}$ C to  $85^{\circ}$ C. The TL384xB-series devices are characterized for operation from  $0^{\circ}$ C to  $70^{\circ}$ C.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

SLVS610B-AUGUST 2006-REVISED JULY 2007



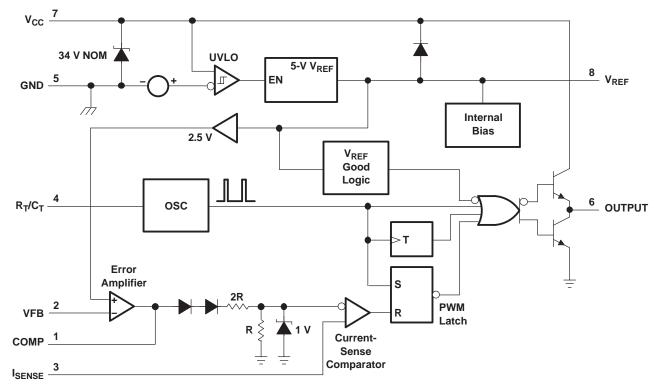
### **ORDERING INFORMATION**

T <sub>A</sub>	PAC	CKAGE <sup>(1)</sup>	ORDERABLE PART NUMBER	TOP-SIDE MARKING		
			TL2842BP	TL2842BP		
	DDID D	Tube of 50	TL2843BP	TL2843BP		
	PDIP – P	Tube of 50	TL2844BP			
			TL2845BP	TL2845BP		
		Tube of 75	TL2842BD-8	0040D		
		Reel of 2500	TL2842BDR-8			
		Tube of 75	TL2843BD-8	2042D		
	COIC D (0 nin)	Reel of 2500	TL2843BDR-8			
	SOIC – D (8 pin)	Tube of 75	TL2844BD-8	2044D		
40°C to 95°C		Reel of 2500	TL2844BDR-8	Z044D		
–40°C to 85°C		Tube of 75	TL2845BD-8	204ED		
		Reel of 2500	TL2845BDR-8			
		Tube of 75	TL2842BD	TI 2942B		
		Reel of 2500	TL2842BDR	TL2042D		
		Tube of 75	TL2843BD	TI 2042D		
	SOIC D (14 pip)	Reel of 2500	TL2843BDR	- IL2043D		
	SOIC – D (14 pin)	Tube of 75	TL2844BD	TI 2044D		
		Reel of 2500	TL2844BDR	1L2044D		
		Tube of 75	TL2845BD	TI 2045D		
		Reel of 2500	TL2845BDR	1L2043D		
			TL3842BP	TL3842BP		
	PDIP – P	Tube of 50	TL3843BP	TL3843BP		
	FDIF - F	Tube of 30	TL3844BP	TL3844BP		
			TL3845BP	TL3845BP		
		Tube of 75	TL3842BD-8	38/2B		
		Reel of 2500	TL3842BDR-8	30420		
		Tube of 75	TL3843BD-8	2042B		
	SOIC - D (8 pin)	Reel of 2500	TL3843BDR-8	3043B		
	301C - D (8 pill)	Tube of 75	TL3844BD-8	2944B		
0°C to 70°C		Reel of 2500	TL3844BDR-8	30440		
0 0 10 70 0		Tube of 75	TL3845BD-8	3845B		
		Reel of 2500	TL3845BDR-8	3043D		
		Tube of 75	TL3842BD	TI 3842B		
		Reel of 2500	TL3842BDR	1 200420		
		Tube of 75	TL3843BD	TI 38//3B		
	SOIC – D (14 pin)	Reel of 2500	TL3843BDR	1 200400		
	0010 - D (14 pill)	Tube of 75	TL3844BD	TI 3844B		
		Reel of 2500	TL3844BDR	1 200440		
		Tube of 75	TL3845BD	TL3845B		
		Reel of 2500	TL3845BDR			

<sup>(1)</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

SLVS610B-AUGUST 2006-REVISED JULY 2007

### **FUNCTIONAL BLOCK DIAGRAM**



A. Pin numbers shown are for the 8-pin D package.

SLVS610B-AUGUST 2006-REVISED JULY 2007



### **Absolute Maximum Ratings**(1)(2)

over operating free-air temperature range (unless otherwise noted)

				MIN	MAX	UNIT
		Low impedance so	urce		30	
V <sub>CC</sub>	Supply voltage	I <sub>CC</sub> < 30 mA			Self limiting	V
VI	Analog input voltage range	VFB and I <sub>SENSE</sub>		-0.3	6.3	V
I <sub>CC</sub>	Supply current				30	mA
Io	Output current				±1	Α
I <sub>O(sink)</sub>	Error amplifier output sink current				10	mA
		Dinaskaga	8 pin		97	
$\theta_{JA}$	Package thermal impedance (3)(4)	D package	14 pin		86	°C/W
		P package			85	
	Output energy	Capacitive load			5	μJ
TJ	Virtual junction temperature				150	°C
T <sub>stg</sub>	Storage temperature range			-65	150	°C
T <sub>lead</sub>	Lead temperature	Soldering, 10 s			300	°C

<sup>(1)</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) All voltages are with respect to the device GND terminal.

### **Recommended Operating Conditions**

			MIN	NOM	MAX	UNIT
\/	Cupply valtage	V <sub>CC</sub>			30	V
V <sub>CC</sub>	Supply voltage	VC <sup>(1)</sup>			30	V
.,	lanut valta sa	R <sub>T</sub> /C <sub>T</sub>	0		5.5	V
VI	Input voltage	VFB and I <sub>SENSE</sub>	0		5.5	V
\/	Output valtage	OUTPUT	0		30	V
Vo	Output voltage	POWER GROUND <sup>(1)</sup>	-0.1		1	V
I <sub>CC</sub>	Supply current, externally limited				25	mA
Io	Average output current				200	mA
I <sub>O(ref)</sub>	Reference output current				-20	mA
f <sub>osc</sub>	Oscillator frequency			100	500	kHz
т	Operating free oir temperature	TL284xB	-40		85	°C
$T_J$	Operating free-air temperature	TL384xB	0		70	C

<sup>(1)</sup> The recommended voltages for VC and POWER GROUND apply only to the 14-pin D package.

<sup>(3)</sup> Maximum power dissipation is a function of  $T_J(max)$ ,  $\theta_{JA}$ , and  $T_A$ . The maximum allowable power dissipation at any allowable ambient temperature is  $P_D = (T_J(max) - T_A)/\theta_{JA}$ . Operating at the absolute maximum  $T_J$  of 150°C can impact reliability.

<sup>(4)</sup> The package thermal impedance is calculated in accordance with JESD 51-7.



SLVS610B-AUGUST 2006-REVISED JULY 2007

### **Reference Section Electrical Characteristics**

 $V_{CC}$  = 15  $V^{(1)}$ ,  $R_T$  = 10  $k\Omega$ ,  $C_T$  = 3.3 nF, over recommended operating free-air temperature range (unless otherwise specified)

DADAMETED	TEST COMPLETIONS		TL284xB		•	TL384xB		LINUT
PARAMETER	TEST CONDITIONS	MIN	TYP <sup>(2)</sup>	MAX	MIN	TYP <sup>(2)</sup>	MAX	UNIT
Output voltage	I <sub>O</sub> = 1 mA, T <sub>J</sub> = 25°C	4.95	5	5.05	4.9	5	5.1	V
Line regulation	V <sub>CC</sub> = 12 V to 25 V		6	20		6	20	mV
Load regulation	$I_O = 1$ mA to 20 mA		6	25		6	25	mV
Average temperature coefficient of output voltage			0.2	0.4		0.2	0.4	mV/°C
Output voltage, worst-case variation	$V_{CC} = 12 \text{ V to } 25 \text{ V},$ $I_{O} = 1 \text{ mA to } 20 \text{ mA}$	4.9		5.1	4.82		5.18	٧
Output noise voltage	$f = 10 \text{ Hz to } 10 \text{ kHz}, T_J = 25^{\circ}\text{C}$		50			50		μV
Output-voltage long-term drift	After 1000 h at T <sub>J</sub> = 25°C		5	25		5	25	mV
Short-circuit output current		-30	-100	-180	-30	-100	-180	mA

<sup>(1)</sup> Adjust  $V_{CC}$  above the start threshold before setting it to 15 V.

### Oscillator Section<sup>(1)</sup> Electrical Characteristics

 $V_{CC}$  = 15  $V^{(2)}$ ,  $R_T$  = 10  $k\Omega$ ,  $C_T$  = 3.3 nF, over recommended operating free-air temperature range (unless otherwise specified)

DADAMETED	TEST COMPITIONS		TL284xB			TL384xB		LINUT
PARAMETER	TEST CONDITIONS	MIN	TYP <sup>(3)</sup>	MAX	MIN	TYP <sup>(3)</sup>	MAX	UNIT
	T <sub>J</sub> = 25°C	49	52	55	49	52	55	
Initial accuracy	$T_A = T_{low}$ to $T_{high}$	48		56	48		56	kHz
Timal accuracy	$T_J = 25^{\circ}C$ , $R_T = 6.2 \text{ k}\Omega$ , $C_T = 1 \text{ nF}$	225	250	275	225	250	275	<u>-</u>
Voltage stability	V <sub>CC</sub> = 12 V to 25 V		0.2	1		0.2	1	%
Temperature stability			5			5		%
Amplitude	Peak to peak		1.7			1.7		V
Diagharma aurrant	$T_J = 25^{\circ}C, R_T/C_T = 2 V$	7.8	8.3	8.8	7.8	8.3	8.8	A
Discharge current	$R_T/C_T = 2 V$	7.5		8.8	7.6		8.8	mA

<sup>(1)</sup> Output frequency equals oscillator frequency for the TL3842B and TL3843B. Output frequency is one-half the oscillator frequency for the TL3844B and TL3845B.

<sup>(2)</sup> All typical values are at  $T_J = 25$ °C.

<sup>(2)</sup> Adjust  $V_{CC}$  above the start threshold before setting it to 15 V.

<sup>(3)</sup> All typical values are at  $T_J = 25$ °C.

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SLVS610B-AUGUST 2006-REVISED JULY 2007

### **Error-Amplifier Section Electrical Characteristics**

 $V_{CC}$  = 15  $V^{(1)}$ ,  $R_T$  = 10  $k\Omega$ ,  $C_T$  = 3.3 nF, over recommended operating free-air temperature range (unless otherwise specified)

PARAMETER	TEST CONDITIONS		TL284xB			TL384xB		UNIT
PARAMETER	TEST CONDITIONS	MIN	TYP <sup>(2)</sup>	MAX	MIN	TYP <sup>(2)</sup>	MAX	UNIT
Feedback input voltage	COMP = 2.5 V	2.45	2.5	2.55	2.42	2.5	2.58	V
Input bias current			-0.3	-1		-0.3	-2	μA
Open-loop voltage amplification	V <sub>O</sub> = 2 V to 4 V	65	90		65	90		dB
Gain-bandwidth product		0.7	1		0.7	1		MHz
Supply-voltage rejection ratio	V <sub>CC</sub> = 12 V to 25 V	60	70		60	70		dB
Output sink current	VFB = 2.7 V, COMP = 1.1 V	2	6		2	6		mA
Output source current	VFB = 2.3 V, COMP = 5 V	-0.5	-0.8		-0.5	-0.8		mA
High-level output voltage	VFB = 2.3 V, R <sub>L</sub> = 15 kΩ to GND	5	6		5	6		V
Low-level output voltage	VFB = 2.7 V, R <sub>L</sub> = 15 kΩ to GND		0.7	1.1		0.7	1.1	V

<sup>(1)</sup> Adjust  $V_{CC}$  above the start threshold before setting it to 15 V. (2) All typical values are at  $T_J = 25^{\circ}C$ .

### **Current-Sense Section Electrical Characteristics**

 $V_{CC} = 15 \text{ V}^{(1)}, R_T = 10 \text{ k}\Omega, C_T = 3.3 \text{ nF}, \text{ over recommended operating free-air temperature range (unless otherwise specified)}$ 

DADAMETED	TEST COMPITIONS		TL284xB			TL384xB		UNIT	
PARAMETER	TEST CONDITIONS	MIN	TYP <sup>(2)</sup>	MAX	MIN	TYP <sup>(2)</sup>	MAX	UNII	
Voltage amplification (3)(4)		2.85	3	3.15	2.85	3	3.15	V/V	
Current-sense comparator threshold (3)	COMP = 5 V	0.9	1	1.1	0.9	1	1.1	V	
Supply-voltage rejection ratio (3)	V <sub>CC</sub> = 12 V to 25 V		70			70		dB	
Input bias current			-2	-10		-2	-10	μA	
Delay time to output	VFB = 0 V to 2 V		150	300		150	300	ns	

<sup>(1)</sup> Adjust  $V_{CC}$  above the start threshold before setting it to 15 V.

<sup>(2)</sup> All typical values are at T<sub>J</sub> = 25°C.

<sup>(3)</sup> Measured at the trip point of the latch, with VFB at 0 V.

<sup>(4)</sup> Measured between I<sub>SENSE</sub> and COMP, with the input changing from 0 V to 0.8 V.



SLVS610B-AUGUST 2006-REVISED JULY 2007

### **Output Section Electrical Characteristics**

 $V_{CC} = 15 \text{ V}^{(1)}$ ,  $R_T = 10 \text{ k}\Omega$ ,  $C_T = 3.3 \text{ nF}$ , over recommended operating free-air temperature range (unless otherwise specified)

PARAMETER	TEST CONDITIONS		TL284xB			TL384xB		UNIT
PARAMETER	TEST CONDITIONS	MIN	TYP <sup>(2)</sup>	MAX	MIN	TYP <sup>(2)</sup>	MAX	UNII
High level output voltage	I <sub>OH</sub> = -20 mA	13	13.5		13	13.5		V
High-level output voltage	I <sub>OH</sub> = -200 mA	12	13.5		12	13.5		V
Low lovel output voltage	I <sub>OL</sub> = 20 mA		0.1	0.4		0.1	0.4	V
Low-level output voltage	I <sub>OL</sub> = 200 mA		1.5	2.2		1.5	2.2	V
Rise time	$C_L = 1 \text{ nF}, T_J = 25^{\circ}\text{C}$		50	150		50	150	ns
Fall time	$C_L = 1 \text{ nF, } T_J = 25^{\circ}C$		50	150		50	150	ns
UVLO saturation	$V_{CC} = 5 \text{ V}, I_{OL} = 1 \text{ mA}$		0.7	1.2		0.7	1.2	V

<sup>(1)</sup> Adjust  $V_{CC}$  above the start threshold before setting it to 15 V.

### **Undervoltage-Lockout Section Electrical Characteristics**

 $V_{CC} = 15 \text{ V}^{(1)}$ ,  $R_T = 10 \text{ k}\Omega$ ,  $C_T = 3.3 \text{ nF}$ , over recommended operating free-air temperature range (unless otherwise specified)

DADAMETED	TEST CONDITIONS		TL284xB		TL384xB			UNIT
PARAMETER	TEST CONDITIONS	MIN	TYP <sup>(2)</sup>	MAX	MIN	TYP <sup>(2)</sup>	MAX	UNIT
Start threshold voltage	TLx842B, TLx844B	15	16	17	14.5	16	17.5	V
Start tilleshold voltage	TLx843B, TLx845B	7.8	8.4	9	7.8	8.4	9	V
Minimum operating voltage	TLx842B, TLx844B	9	10	11	8.5	10	11.5	\/
after start-up	TLx843B, TLx845B	7	7.6	8.2	7	7.6	8.2	V

<sup>(1)</sup> Adjust  $V_{CC}$  above the start threshold before setting it to 15 V.

### **Pulse-Width Modulator Section Electrical Characteristics**

 $V_{CC}$  = 15  $V^{(1)}$ ,  $R_T$  = 10  $k\Omega$ ,  $C_T$  = 3.3 nF, over recommended operating free-air temperature range (unless otherwise specified)

PARAMETER	TEST CONDITIONS	•	TL284xB		TL384xB			UNIT
PARAMETER	TEST CONDITIONS	MIN	TYP <sup>(2)</sup>	MAX	MIN	TYP <sup>(2)</sup>	MAX	UNII
Maximum duty avala	TL3842B, TL3843B	94	96	100	94	96	100	%
Maximum duty cycle	TL3844B, TL3845B	47	48	50	47	48	50	70
Minimum duty cycle				0			0	%

<sup>(1)</sup> Adjust  $V_{CC}$  above the start threshold before setting it to 15 V.

### **Supply Voltage Electrical Characteristics**

 $V_{CC}$  = 15  $V^{(1)}$ ,  $R_T$  = 10  $k\Omega$ ,  $C_T$  = 3.3 nF, over recommended operating free-air temperature range (unless otherwise specified)

PARAMETER	TEST CONDITIONS		TL284xB		•		UNIT	
PARAMETER	TEST CONDITIONS	MIN	TYP <sup>(2)</sup>	MAX	MIN	TYP <sup>(2)</sup>	MAX	UNIT
Start-up current			0.3	0.5		0.3	0.5	mA
Operating supply current	VFB and I <sub>SENSE</sub> at 0 V		11	17		11	17	mA
Limiting voltage	I <sub>CC</sub> = 25 mA	30	34		30	34		V

<sup>(1)</sup> Adjust  $V_{CC}$  above the start threshold before setting it to 15 V.

<sup>(2)</sup> All typical values are at  $T_J = 25$ °C.

<sup>(2)</sup> All typical values are at T<sub>J</sub> = 25°C.

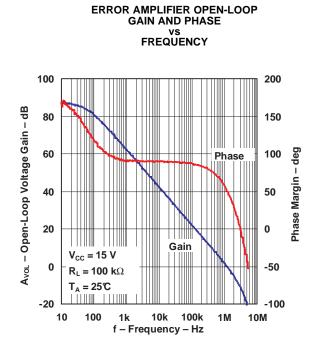
<sup>(2)</sup> All typical values are at  $T_J = 25$ °C.

<sup>(2)</sup> All typical values are at  $T_J = 25$ °C.



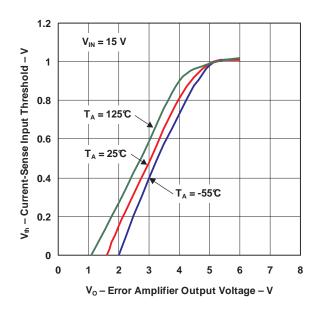
### TYPICAL CHARACTERISTICS

SUPPLY CURRENT vs SUPPLY VOLTAGE 25 20 Icc - Supply Current - mA 15 10 TL2842 TL2845 5 0 0 5 15 20 25 30 35 40 10

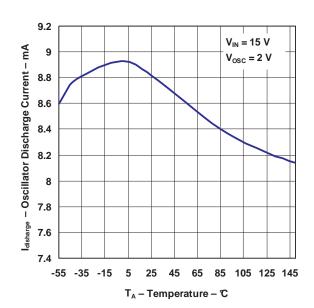


# CURRENT-SENSE INPUT THRESHOLD VS ERROR AMPLIFIER OUTPUT VOLTAGE

V<sub>cc</sub> - Supply Voltage - V

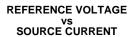


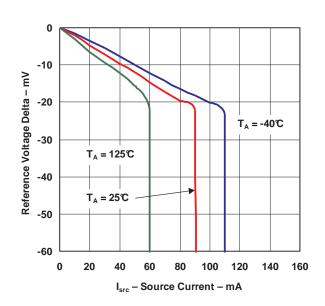
## OSCILLATOR DISCHARGE CURRENT vs TEMPERATURE



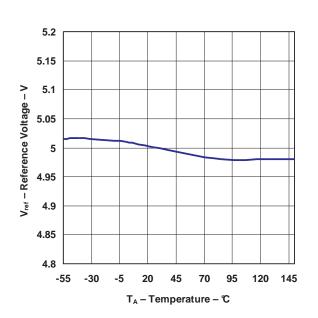
SLVS610B-AUGUST 2006-REVISED JULY 2007

### **TYPICAL CHARACTERISTICS (continued)**

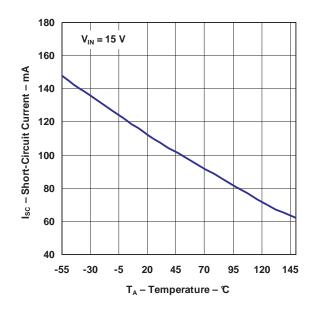




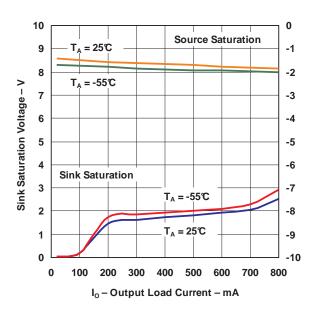
# REFERENCE VOLTAGE vs TEMPERATURE



## REFERENCE SHORT-CIRCUIT CURRENT vs TEMPERATURE



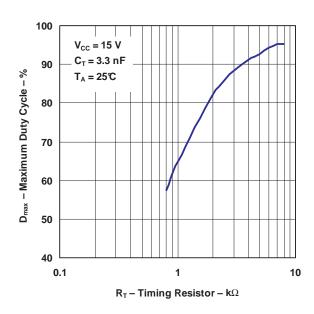
## OUTPUT SATURATION VOLTAGE VS LOAD CURRENT

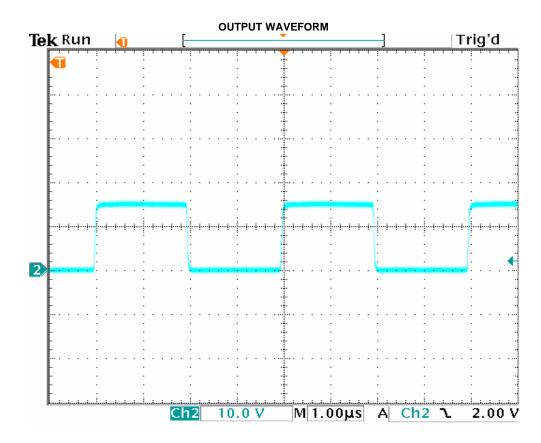




### **TYPICAL CHARACTERISTICS (continued)**

# MAXIMUM OUTPUT DUTY CYCLE vs TIMING RESISTOR

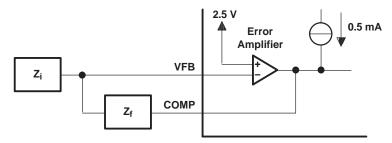




SLVS610B-AUGUST 2006-REVISED JULY 2007

### **APPLICATION INFORMATION**

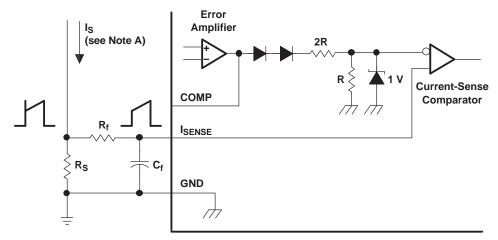
The error-amplifier configuation circuit is shown in Figure 1.



A. Error amplifier can source or sink up to 0.5 mA.

Figure 1. Error-Amplifier Configuration

The current-sense circuit is shown in Figure 2.



- A. Peak current ( $I_S$ ) is determined by the formula:  $I_{S(max)} = 1 \text{ V/R}_S$
- B. A small RC filter formed by resistor R<sub>f</sub> and capacitor C<sub>f</sub> may be required to suppress switch transients.

Figure 2. Current-Sense Circuit

The oscillator frequency is set using the circuit shown in Figure 3. The frequency is calculated as:

$$f = 1 / R_T C_T$$

For  $R_T > 5 \text{ k}\Omega$ :

 $f \approx 1.72 / R_T C_T$ 

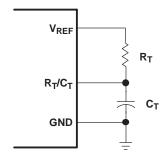
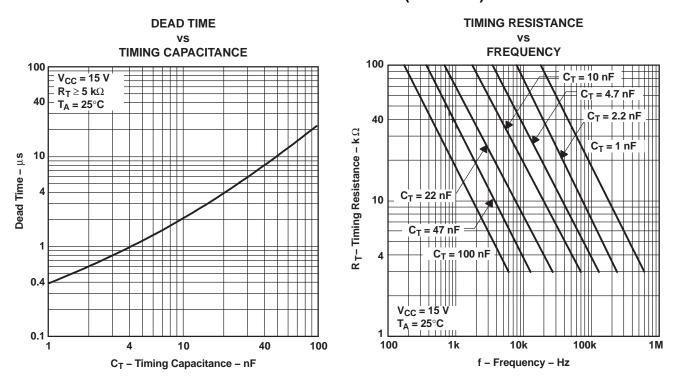


Figure 3. Oscillator Section



### **APPLICATION INFORMATION (continued)**



### **Open-Loop Laboratory Test Fixture**

In the open-loop laboratory test fixture (see Figure 4), high peak currents associated with loads necessitate careful grounding techniques. Timing and bypass capacitors should be connected close to the GND terminal in a single-point ground. The transistor and  $5-k\Omega$  potentiometer sample the oscillator waveform and apply an adjustable ramp to the  $I_{SENSE}$  terminal.

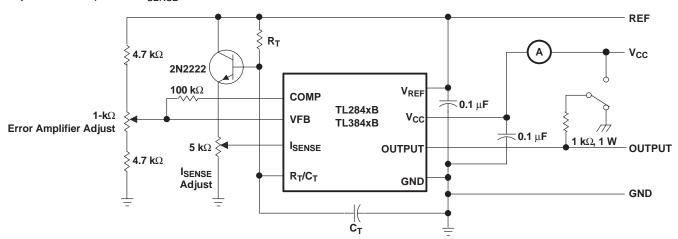


Figure 4. Open-Loop Laboratory Test Fixture

SLVS610B-AUGUST 2006-REVISED JULY 2007

### **APPLICATION INFORMATION (continued)**

### **Shutdown Technique**

The PWM controller (see Figure 5) can be shut down by two methods: either raise the voltage at  $I_{SENSE}$  above 1 V or pull the COMP terminal below a voltage two diode drops above ground. Either method causes the output of the PWM comparator to be high (refer to block diagram). The PWM latch is reset dominant so that the output remains low until the next clock cycle after the shutdown condition at the COMP or  $I_{SENSE}$  terminal is removed. In one example, an externally latched shutdown can be accomplished by adding an SCR that resets by cycling  $V_{CC}$  below the lower UVLO threshold. At this point, the reference turns off, allowing the SCR to reset.

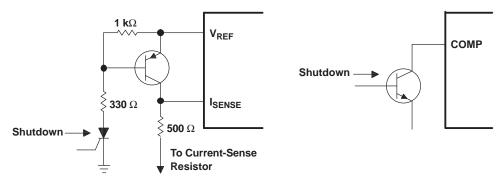


Figure 5. Shutdown Techniques

A fraction of the oscillator ramp can be summed resistively with the current-sense signal to provide slope compensation for converters requiring duty cycles over 50% (see Figure 6). Note that capacitor C forms a filter with R2 to suppress the leading-edge switch spikes.

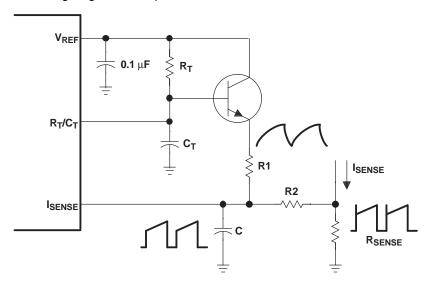


Figure 6. Slope Compensation



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### **PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
TL2842BD	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	TL2842B	Samples
TL2842BD-8	ACTIVE	SOIC	D	8	75	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	2842B	Samples
TL2842BDR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	TL2842B	Samples
TL2842BDR-8	ACTIVE	SOIC	D	8	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	2842B	Samples
TL2842BP	ACTIVE	PDIP	Р	8	50	RoHS & Green	NIPDAU	N / A for Pkg Type	-40 to 85	TL2842BP	Samples
TL2843BD	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	TL2843B	Samples
TL2843BD-8	ACTIVE	SOIC	D	8	75	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	2843B	Samples
TL2843BDR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	TL2843B	Samples
TL2843BDR-8	ACTIVE	SOIC	D	8	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	2843B	Samples
TL2843BDRG4-8	ACTIVE	SOIC	D	8	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	2843B	Samples
TL2843BP	ACTIVE	PDIP	Р	8	50	RoHS & Green	NIPDAU	N / A for Pkg Type	-40 to 85	TL2843BP	Samples
TL2844BD-8	ACTIVE	SOIC	D	8	75	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	2844B	Samples
TL2844BDR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	TL2844B	Samples
TL2844BDR-8	ACTIVE	SOIC	D	8	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	2844B	Samples
TL2844BDRG4-8	ACTIVE	SOIC	D	8	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	2844B	Samples
TL2845BD	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	TL2845B	Samples
TL2845BD-8	ACTIVE	SOIC	D	8	75	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	2845B	Samples
TL2845BDR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	TL2845B	Samples
TL2845BDR-8	ACTIVE	SOIC	D	8	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	2845B	Samples
TL2845BDRG4-8	ACTIVE	SOIC	D	8	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	2845B	Samples





www.ti.com

13-Aug-2021

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
TL3842BD	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	TL3842B	Samples
TL3842BD-8	ACTIVE	SOIC	D	8	75	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	3842B	Samples
TL3842BDR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	TL3842B	Samples
TL3842BDR-8	ACTIVE	SOIC	D	8	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	3842B	Samples
TL3842BP	ACTIVE	PDIP	Р	8	50	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	TL3842BP	Samples
TL3843BD	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	TL3843B	Samples
TL3843BD-8	ACTIVE	SOIC	D	8	75	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	3843B	Samples
TL3843BDR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	TL3843B	Samples
TL3843BDR-8	ACTIVE	SOIC	D	8	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	3843B	Samples
TL3843BDRG4	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	TL3843B	Samples
TL3843BP	ACTIVE	PDIP	Р	8	50	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	TL3843BP	Samples
TL3844BD-8	ACTIVE	SOIC	D	8	75	RoHS & Green	NIPDAU	Level-1-260C-UNLIM 0 to 70		3844B	Samples
TL3844BDR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	TL3844B	Samples
TL3844BDR-8	ACTIVE	SOIC	D	8	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	3844B	Samples
TL3844BP	ACTIVE	PDIP	Р	8	50	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	TL3844BP	Samples
TL3845BD	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	TL3845B	Samples
TL3845BD-8	ACTIVE	SOIC	D	8	75	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	3845B	Samples
TL3845BDR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	TL3845B	Samples
TL3845BDR-8	ACTIVE	SOIC	D	8	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	3845B	Samples
TL3845BP	ACTIVE	PDIP	Р	8	50	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	TL3845BP	Samples

<sup>(1)</sup> The marketing status values are defined as follows:

### PACKAGE OPTION ADDENDUM

www.ti.com 13-Aug-2021

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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#### OTHER QUALIFIED VERSIONS OF TL2843B:

Automotive: TL2843B-Q1

NOTE: Qualified Version Definitions:

Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects



www.ti.com 3-Aug-2021

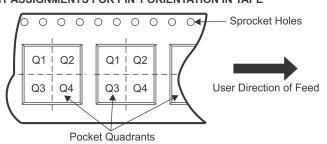
### TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

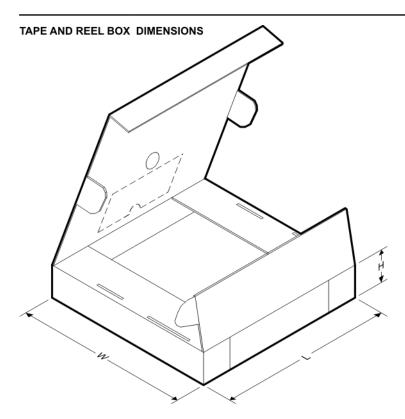


#### \*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TL2842BDR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
TL2842BDR-8	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TL2843BDR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
TL2843BDR-8	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TL2844BDR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
TL2844BDR-8	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TL2845BDR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
TL2845BDR-8	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TL3842BDR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
TL3842BDR-8	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TL3843BDR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
TL3843BDR-8	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TL3844BDR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
TL3844BDR-8	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TL3845BDR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
TL3845BDR-8	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1



www.ti.com 3-Aug-2021



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TL2842BDR	SOIC	D	14	2500	853.0	449.0	35.0
TL2842BDR-8	SOIC	D	8	2500	340.5	336.1	25.0
TL2843BDR	SOIC	D	14	2500	853.0	449.0	35.0
TL2843BDR-8	SOIC	D	8	2500	340.5	336.1	25.0
TL2844BDR	SOIC	D	14	2500	853.0	449.0	35.0
TL2844BDR-8	SOIC	D	8	2500	340.5	336.1	25.0
TL2845BDR	SOIC	D	14	2500	853.0	449.0	35.0
TL2845BDR-8	SOIC	D	8	2500	340.5	336.1	25.0
TL3842BDR	SOIC	D	14	2500	853.0	449.0	35.0
TL3842BDR-8	SOIC	D	8	2500	340.5	336.1	25.0
TL3843BDR	SOIC	D	14	2500	853.0	449.0	35.0
TL3843BDR-8	SOIC	D	8	2500	340.5	336.1	25.0
TL3844BDR	SOIC	D	14	2500	853.0	449.0	35.0
TL3844BDR-8	SOIC	D	8	2500	340.5	336.1	25.0
TL3845BDR	SOIC	D	14	2500	853.0	449.0	35.0
TL3845BDR-8	SOIC	D	8	2500	340.5	336.1	25.0

### D (R-PDSO-G14)

### PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.



## D (R-PDSO-G14)

### PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.





SMALL OUTLINE INTEGRATED CIRCUIT



- 1. Linear dimensions are in inches [millimeters]. Dimensions in parenthesis are for reference only. Controlling dimensions are in inches. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 [0.15] per side.
- 4. This dimension does not include interlead flash.
- 5. Reference JEDEC registration MS-012, variation AA.



SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE INTEGRATED CIRCUIT



#### NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



### P (R-PDIP-T8)

### PLASTIC DUAL-IN-LINE PACKAGE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MS-001 variation BA.



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